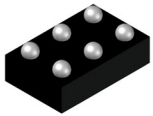


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

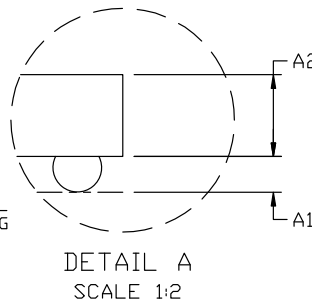
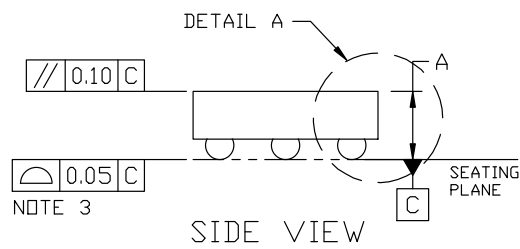
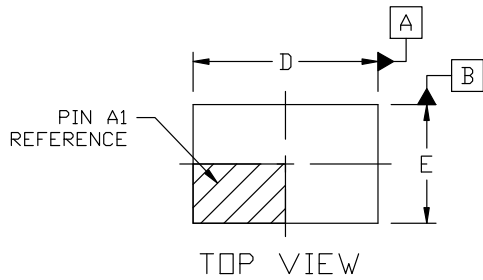


WLCSP6 1.40x0.90x0.516
CASE 567KB
ISSUE C

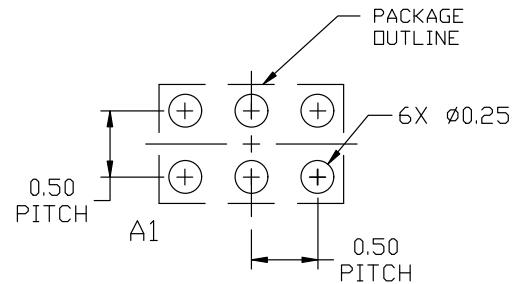
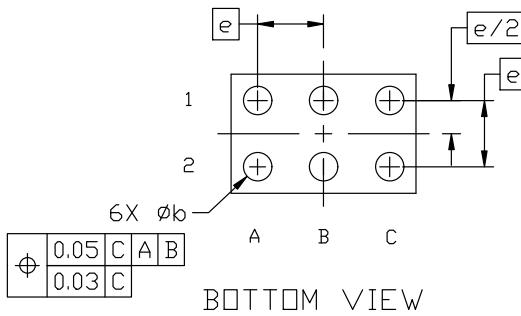
DATE 21 JUN 2022

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.478	0.516	0.554
A1	0.136	0.156	0.176
A2	0.342	0.360	0.378
b	0.194	0.214	0.234
D	1.360	1.400	1.440
E	0.860	0.900	0.940
e	0.50 BSC		



RECOMMENDED
MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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